

e.MMC-Based MCP

MT29VZZZAD8GUFSL-046-W.219 part detail

Documents

+ Data Sheet	
+ Reach Statement	
+ RoHS	
+ Sim Model	

Specifications

Component Density 544Gb	I/O Voltage 1.2VOLTS	Protocol MMC5.1	Operating Temp -25C to +85 C	Pin Count 254-ball	Part Status Code Contact Sal es
Dry Pack Qty 1520	Package Dimension (W x L x H) mm	Tape & Reel Qty	Number of Components	Package Type GREEN	Technology eMCP TLC LPDDR4



Package Family **VFBGA MCP**



Products Markets & Industries Sales & Support About Investor relations Partners 4 8 1



CONTACT US

SALES SUPPORT CONTACT

TECHNICAL SUPPORT CONTACT

Legal Your privacy choices Careers

Micron privacy notice

Suppliers

11.50 x 13.0

O x 0.90

Terms and conditions of sale

@2025 Micron Technology, Inc. All rights reserved. Information, products, and/or specifications are subject to change without notice. All information is provided on an "AS IS" basis without warranties of any kind. Drawings may not be to scale. Micron, the Micron logo, and all other Micron trademarks are the property of Micron Technology, Inc. All other trademarks are the property of their respective